

MAINTENANCE MANUAL

851-870 MHz MASTR® II STATION EXCITER BOARD 19D424075GI

TABLE OF CONTENTS—	
	Page
DESCRIPTION	1
CIRCUIT ANALYSIS	1
OUTLINE DIAGRAM (Exciter Board 19D424075G1)	4
SCHEMATIC DIAGRAM (Exciter Board 19D424075G1)	5
OUTLINE & SCHEMATIC DIAGRAM (Audio Processor 19C321542G1)	7
PARTS LIST AND PRODUCTION CHANGES	6

DESCRIPTION

The exciter assembly contains the oscillator, the audio processor, the modulator and all frequency multiplier functions. The exciter delivers the transmitter carrier frequency at its output. The oscillator module provides ±1 PPM stability and plugs into the exciter board at XY101. The audio processor module plugs into the exciter board at XA101.

Modulation is accomplished on this exciter by a single-section phase modulator. The multiplier stages multiply the oscillator frequency by a factor of 48 times. Audio, control and supply voltages are connected to the exciter through P902.

Centralized metering jack J103 is provided for use with GE Test Set Model 4EX3All or Test Kit 4EX8Kl2. The test set meters the modulator, the multiplier stages and relative output voltage.

CIRCUIT ANALYSIS

1 PPM ICOM (Y101)

The quartz crystal used in the ICOM exhibits the traditional "S" curve characteristics of output frequency versus operating temperature. Rated stability (± 1 PPM) of the ICOM is maintained over a temperature range of $-30\,^{\circ}\text{C}$ to $+85\,^{\circ}\text{C}$.

At both the coldest and hottest temperatures, the frequency increases with increasing temperature. In the middle temperature range (approximately 0°C to 55°C), frequency decreases with increasing temperature.

Since the rate of change is nearly linear over the mid-temperature range, the output frequency change can be compensated by choosing a parallel compensation capacitor with a temperature coefficient approximately equal and opposite that of the crystal.

Figure 1 shows the typical performance of an uncompensated crystal as well as the typical performance of a crystal which has been matched with a properly chosen compensation capacitor.

At temperatures above and below the mid-range, additional compensation must be introduced. An externally generated compensation voltage is applied to a varactor (voltage-variable capacitor) which is in parallel with the crystal.

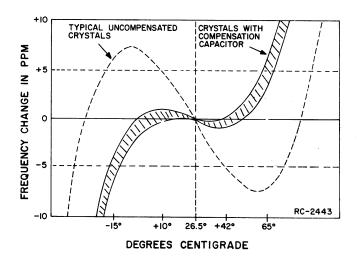


Figure 1 - Typical Crystal Characteristics



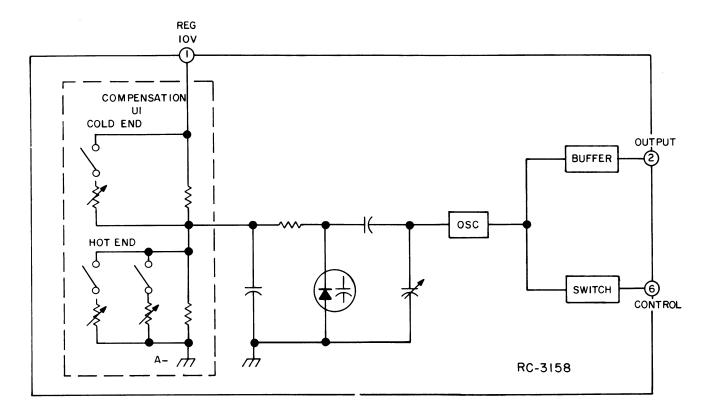


Figure 2 - Equivalent ICOM Circuit

Compensator Circuits

The ICOM is temperature compensated at both ends of the temperature range to provide instant frequency compensation. An equivalent ICOM circuit is shown in Figure 2.

The cold end compensation circuit does not operate at temperatures above 0°C. When the temperature drops below 0°C, the circuit is activated. As the temperature decreases, the equivalent resistance decreases and the compensation voltage increases.

The increase in compensation voltage decreases the capacity of the varactor in the oscillator, increasing the output frequency of the ICOM.

The hot end compensation circuit does not operate below 55°C. The hot end compensation circuit consists of two branches; the first branch is activated at +55°C and the second branch is activated at +70°C so that both branches are now operating. At temperatures above these activation points, the equivalent resistance decreases thereby decreasing the compensation voltage. This increases the capacitance of the varicap thus reducing the output frequency of the ICOM.

SERVICE NOTE: Proper ICOM operation is dependent on the closely-controlled input voltages from the 10-Volt regulator. Should the ICOM shift off frequency, check the 10-Volt regulator module or check output of the ICOM.

--CAUTION----

The ICOMS are individually compensated at the factory and cannot be repaired in the field. Any attempt to repair or change an ICOM frequency will void the warranty.

AUDIO PROCESSOR A101

The transmitter audio processor contains audio circuitry consisting of two operational amplifiers, AR101-A and -B, a pre-emphasis circuit with amplitude limiting and a post limiter filter. A total gain of approximately 24 dB is realized through the audio processor. Twenty dB is provided by AR101-B and 4 dB by AR101-A.

The 10-Volt regulator powers the audio processor and applies regulated +10 V thru P102-6 to a voltage divider consisting of

R108 and R110. The +5 V output from the voltage divider establishes the operating reference point for both operational amplifiers. C107 filters noise from the voltage supply to the operational amplifiers.

Resistors R105, R106, and R107 and diodes CR101 and CR102 provide limiting for AR101-B. Diodes CR101 and CR102 are reverse biased by +5 VDC on AR101B-6 and voltage divider network R105, R106 and R107. The voltage divider network provides +7 VDC at the cathode of CR101 and +3 VDC at the anode of CR102. C102 and C103 permit a DC level change between AR101B-7 and the voltage divider network for diode biasing.

When the input signal to AR101B-6 is of a magnitude such that the amplifier output at AR101B-7 does not exceed 4 volts P-P, the amplifier provides a nominal 20 dB gain. When the audio signal level at AR101B-7 exceeds 4 volts PP, diodes CR101 and CR102 conduct on the positive and negative half cycles providing 100% negative feedback to reduce the amplifier gain to 1. This limits the audio amplitude at AR101B-7 to 5 volts PP.

Resistors R102, R103, and R104 and C104 comprise the audio pre-emphasis network that enhances the overall system signal to noise ratio. R104 and C104 control the pre-emphasis curve below limiting. R103 and C104 control the cut-off point for high frequency pre-emphasis. As high frequencies are attenuated, the gain of AR101 is increased.

Audio from the microphone is applied to the audio processor at Pl02-1 and coupled to the input of operational amplifier AR101-B through R101 and C101.

The amplified output of AR101-B is coupled through P102-4, audio MOD ADJ control R103 (on the Exciter Board), C106, R112 and R113 to a second operational amplifier AR101-A. Audio MOD ADJ control is set for a deviation of 415 kHz.

The Channel Guard tone input is applied to the audio processor through P902-2, CG MOD ADJ R102 (on the Exciter Board) to P102-5. The CG tone is then coupled through C105 and R111 to AR101A-2 where it is combined with the microphone audio. AR101-A provides a signal gain of approximately 4 dB.

An active post limiter filter consisting of AR101A, R112-R114, C108, and C109 provide 12 dB per octave roll off. R109 and C111 provide an additional 6 dB per octave roll off for a total of 18 dB per octave.

SERVICE NOTE-

R112-R114 are 1% resistors. This tolerance must be maintained to assure proper operation of the post limiter filter. Use exact replacements.

The output of the post limiter filter is coupled through C110 and P102-9 to the de-emphasis audio amplifier Q108. RT101, with a nominal resistance of 50-ohms from 25°C to 70°C, maintains a constant modulation index over the normal operating temperature range. The resistance of RT101 increases with a decrease in temperature below 25°C, thereby decreasing the signal drive to audio amplifier Q108. Audio amplifier Q108 has a nominal gain of 2.

The temperature compensated audio is coupled through Clo8 to the input of the phase modulator circuit. The oscillator output at XY101-2 is coupled through Cll3 and buffer amplifier Ql01 to the input of the phase modulator circuit.

PHASE MODULATOR AND MULTIPLIERS

The phase modulator is varactor (voltage-variable capacitor) CR101 in series with tunable coil L103. This network appears as a series-resonant circuit to the RF output of the oscillator. The audio signal applied to the modulator circuit varies the bias of CR101, resulting in a phase-modulated output.

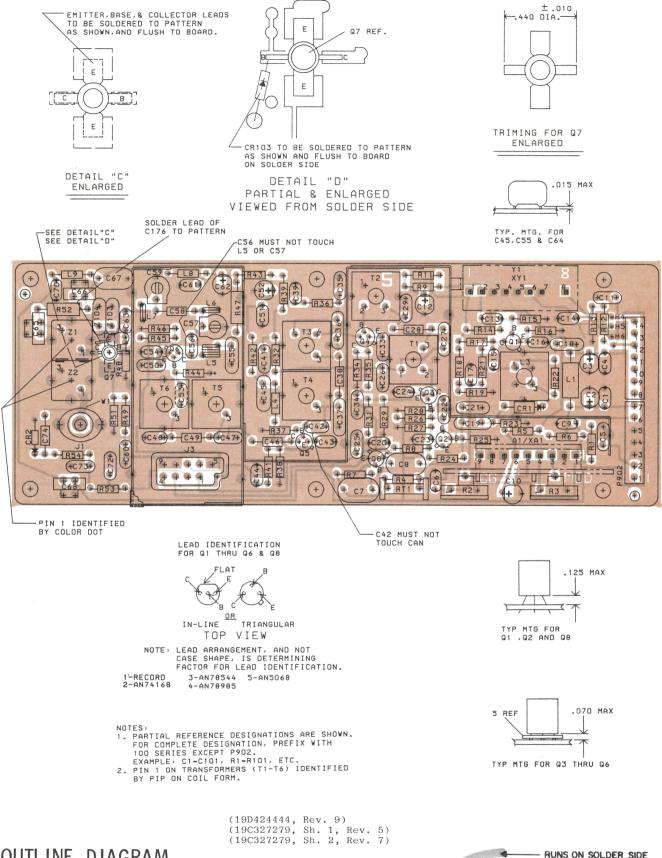
The output of the modulator is coupled through C119 to the base of the second buffer Q102. The output of Q102 is coupled through C122 to the base of the first doubler Q103. The output of Q103 is coupled through tuned circuits T101 and T102 to the base of doubler Q104. The modulated signal is passed through two more doublers (Q105 and Q106) and a tripler (Q107) for a total multiplication factor of 48. The output stage is tuned to the station transmitter frequency. Z101 and Z102 are adjusted to match the input of the power amplifier driver.

The phase modulator is metered through R131 in the emitter of the first doubler. The second doubler is metered through R135. The third doubler is metered through R141, and the fourth doubler through R145. The tripler is metered through R149. The relative output voltage of the exciter is metered through a metering network consisting of C174, R154 and CR102.

GENERAL ELECTRIC COMPANY+ MOBILE COMMUNICATIONS DIVISION WORLD HEADQUARTERS+LYNCHBURG, VIRGINIA 24502 U.S.A.

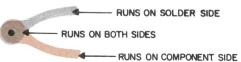


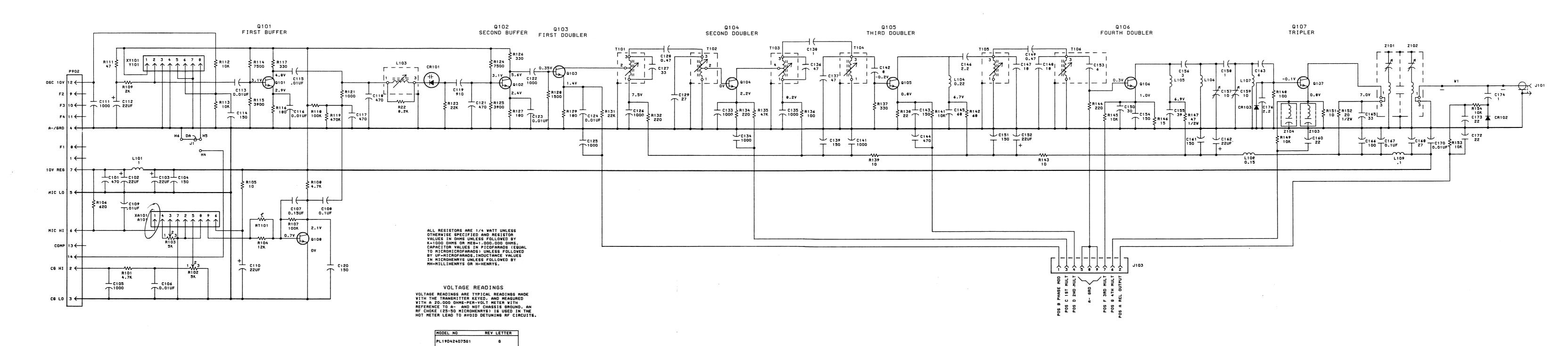
LBI30488



OUTLINE DIAGRAM

851—870 MHz TRANSMITTER EXCITER BOARD 19D424075G1





:. .:

(19R622249, Rev. 10)

SCHEMATIC DIAGRAM

851-870 MHz TRANSMITTER EXCITER BOARD 19D424075G1

LBI30488

PARTS LIST

LBI30484D 851-870 MHz STATIO

SYMBOL GE PART NO. DESCRIPTION 19A116655P13 Ceramic disc: 470 pF $\pm 20\%$, 1000 VDCW; sim to RMC Type JF Discap. Tantalum: 22 uF +20%, 15 VDCW. 19A134202P6 Ceramic disc: 150 pF ±20%, 1000 VDCW; sim to RMC Type JF Discap. C104 19A116655P7 C105 19A116655P19 Ceramic disc: 1000 pF $\pm 20\%$, 1000 VDCW; sim to RMC Type JF Discap. C106 Polyester: 0.01 uF <u>+</u>10%, 50 VDCW C107 Polyester: 0.15 uF +20%, 50 VDCW. 19A116080P8 C108 19A116080P107 Polyester: 0.1 uF <u>+</u>10%, 50 VDCW. C109 L9A700005P7 Polyester: 0.01 uF ±10%, 50 VDCW C110 19A134202P6 Tantalum: 22 uF ±20%, 15 VDCW. Ceramic disc: 1000 pF ±20%, 1000 VDCW; sim to RMC Type JF Discap. C111 19A116655P19 Tantalum: 22 uF ±20%, 15 VDCW. C112 19A134202P6 C113 19A700005P7 Polyester: 0.01 uF +10%, 50 VDCW C114 19A116655P7 Ceramic disc: 150 pF $\pm 20\%,$ 1000 VDCW; sim to RMC Type JF Discap. Polyester: 0.01 uF ±10%, 50 VDCW. 9A700005P7 C117 Ceramic disc: 470 pF ±20%, 1000 VDCW; sim to RMC 19A116655P13 C118 5496372P365 eramic disc: 470 pF ±10%, 500 VDCW, temp coef C119 5496372P379 Ceramic disc: 910 pF \pm 10%, 500 VDCW, temp coef -4700 PPM. C120 19A116655P7 C121 5496372P365 Ceramic disc: 470 pF ±10%, 500 VDCW, temp coef C122 Ceramic disc: 1000 pF $\pm 20\%$, 1000 VDCW; sim to RMC Type JF Discap. 19A116655P19 Polyester: 0.01 uF +10%, 50 VDCW. C125 and C126 Ceramic disc: 1000 pF \pm 20%, 1000 VDCW; sim to RMC Type JF Discap. 19A116655P19 C127 19A116656P33J8 | Ceramic disc: 33 pF ±5%, 500 VDCW, temp coef 9A700013P9 Phenolic: 0.47 pF ±5%, 500 VDCW. C129 Ceramic disc: 27 pF \pm 5%, 500 VDCW, temp coef -80 PPM. 19A116656P27J8 C133 thru C135 19A116655P19 Ceramic disc: 1000 pF ±20%, 1000 VDCW; sim to RMC Type JF Discap. C136 and C137 19A116656P47J8 Ceramic disc: 47 pF ±5%, 500 VDCW; temp coef C138 9A700013P13 Phenolic: 1.00 pF ±5%, 500 VDCW. C139 19A116655P7 Ceramic disc: 1000 pF ±20%, 1000 VDCW; sim to 19A116655P19 19A116656P8J0 Ceramic disc: 8 pF ±0.5 pF, 500 VDCW; temp coef

SYMBOL	GE PART NO.	DESCRIPTION	
C143	19A116655P7	Ceramic disc: 150 pF $\pm 20\%$, 1000 VDCW; sim to Type JF Discap.	
C144	19A116655P13	Ceramic disc: 470 pF $\pm 20\%$, 1000 VDCW; sim to Type JF Discap.	
C145	19A700105P30	Mica: 68 pF ±5%, 500 VDCW.	
C146	5491601P126	Phenolic: 2.2 pF ±5%, 500 VDCW.	
C147	19A116656P18J8	Ceramic disc: 18 pF ±5%, 500 VDCW, temp coe -80 PPM.	
C148	19A116656P15J8	Ceramic disc: 15 pF <u>+</u> 5%, 500 VDCW, temp coe -80 PPM.	
C149	19A700013P9	Phenolic: 0.47 pF ±5%, 500 VDCW.	
C150	194116656030.18	Ceramic disc: 30 pF +5%, 500 VDCW, temp coe	

DESCRIPTION GE PART NO SYMBOL L105 19A130255P4 19A136842P1 Coil, RF: .15 uH \pm 10%, .10 ohms DC res max; sim to Jeffers 4416-3K. 9B209420P103 Coil, RF: .10 uH ±10%, 0.8 ohms DC res max; sim 19B209420P101 to Jeffers 4416-1K. 19B219594P1 Contact, electrical: 7 pins. (Quantity 2). Ceramic disc: 30 pF \pm 5%, 500 VDCW, temp coef -80 PPM. - - - - - - - TRANSISTORS - - - - - -9A700023P1 Silicon, NPN; sim to Type 2N3904. C151 Ceramic disc: 150 pF +20%, 1000 VDCW; sim to RMC Tantalum: 22 uF +20%, 15 VDCW. 19A134202P6 19A115328P1 Silicon, NPN. C153 Ceramic disc: 6 pF ±0.5 pF, 500 VDCW, temp coef 9A116201P3 Silicon, NPN. Ceramic disc: 150 pF \pm 20%, 1000 VDCW; sim to RMC Type JF Discap. 19A116655P7 C155 Mica: 39 pF ±5%, 500 VDCW Q107 9A134430P3 C156 Ceramic disc: 3 pF +0.5 pF, 500 VDCW, temp coef Q108 Silicon, NPN; sim to Type 2N3904 19A116656P3J0 19A700023P1 ariable: 2.04 to 9.9 pF, 250V peak. ----- RESISTORS ------C158 Phenolic: 1.00 pF ±5%, 500 VDCW. R101* 19A700106P79 Composition: 4.7K ohms ±5%, 1/4 w. 19A700013P13 C159 19A700008P1 Variable: 2.04 to 9.9 pF, 250V peak. In REV A & earlier: C160 Composition: 10K ohms ±5%, 1/4 w. 9B209358P105 C161 19A116655P7 Ceramic disc: 150 pF ±20%, 1000 VDCW; sim to RMC C162 19A134202P6 Tantalum: 22 uF ±20%, 15 VDCW. R104 9A700106P89 Composition: 12K ohms ±5%, 1/4 w. Ceramic disc: 6 pF ±0.5 pF, 500 VDCW, temp coef C163 19A116656P6J R105 9A700106P15 Composition: 10 ohms +5%, 1/4 w. R152P621J Frequency network: 400-500 MHz resonant freq. 500 VDCW, sim to Dilectron TC501:NPO:330J:SLAC. R107 9A700106P11 Composition: 100K ohms +5%, 1/4 w. 19A700015P17 Metallized teflon: 33 pF +5%, 250 VDCW. R108 9A700106P79 Composition: 4.7K ohms $\pm 5\%$, 1/4 w. Silver Mica: 100 pF ±10%, 250 VDCW. R109 R152P202J Composition: 2K ohms ±5%, 1/4 w. 19A116080P107 Polyester: 0.1 uF +10%, 50 VDCW. R111 19A700106P31 Composition: 47 ohms +5%, 1/4 w. 19A700015P15 Metallized teflon: 27 pF +10%, 250 VDCW. R112 19A700106P87 Composition: 10K ohms ±5%, 1/4 w. and R113 Ceramic disc: 22 pF ±5%, 500 VDCW, temp coef -80 PPM. 19A116656P22J8 3R152P752J R114 Composition: 7.5K ohms ±5%, 1/4 w. R115 9A700106P77 Composition: 3.9K ohms ±5%, 1/4 w. C174 19A700013P13 Phenolic: 1.00 pF ±5%, 500 VDCW. R116 19A700106P45 Composition: 180 ohms +5%, 1/4 w. C176 19A134100P20 Ceramic disc: 2.2 pF ±0.1 pF, temp coef 0 +120 PPM. R117 9A700106P51 Composition: 330 ohms ±5%, 1/4 w. R118 9A700106P11 ----- DIODES AND RECTIFIERS ----- R119 Composition: 470K ohms ±5%, 1/4 w. R152P474J CR101 5495769P8 9A700106P63 composition: 1K ohms ±5%, 1/4 w. CR102 icon, fast recovery; sim to Hewlett Packard R122 Composition: 8.2K ohms ±5%, 1/4 w. 9A700106P85 9A700106P95 Composition: 22K ohms +5%, 1/4 w. CR103* 19A116052P2 Silicon, fast recovery; sim to Hewlett Packard 5082-2811. Added by REV C. R152P752J Composition: 7.5K ohms ±5%, 1/4 w. 9A700106P77 Composition: 3.9K ohms +5%, 1/4 w. - - - - - JACKS AND RECEPTACLES - - - - -9A700106P51 Composition: 330 ohms ±5%, 1/4 w. 19A700049P2 Connector, receptacle, 500 VDCW maximum; sim to 9A700106P45 Composition: 180 ohms ±5%, 1/4 w. Connector, 9 contacts. Includes: Shell. 19B219374G1 9A700106P67 Composition: 1.5K ohms $\pm 5\%$, 1/4 w. 9A700106P45 Composition: 180 ohms ±5%, 1/4 w. - - - - - - - INDUCTORS - - - - - -9A700106P95 Composition: 22K ohms +5%, 1/4 w. L101 19A700000P12 Coil, RF: 1.0 uH ±10%. 9A700106P47 Composition: 220 ohms ±5%, 1/4 w. 19C307171P103 Coil, RF: variable, wire size No. 34 AWG; sim to Paul Smith 111875-DS-1. 9A700106P47 omposition: 220 ohms ±5%, 1/4 w. oil, RF: .22 uH ±10%, .14 ohms DC res max; sim R135 9A700106P10 Composition: 47K ohms +5%, 1/4 w. 9A700106P39 Composition: 100 ohms ±5%, 1/4 w. 9A700106P51 Composition: 330 ohms ±5%, 1/4 w.

Connector, printed wiring: 9 contacts rated at 5 amps; sim to Molex 09-52-3091. T101 19C307170P305 Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith 092574-DS-2. P102 19A116659P76 T102 19C307170P307 Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith 092574-DS-4. Variable, carbon film: approx 200 to 5K ohms ±10%, 1/4 w; sim to CTS Type X-201. Deposited carbon: 22K ohms +5%, 1/8 w. T103 R101 19A134231P223J 19C307169P202 oil, RF: variable, wire size No. 20 AWG; sim to 19A700106P95 Composition: 22K ohms $\pm 5\%$, 1/4 w. T104 Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith 092574-DS-6. 19C307169P203 19A700106P55 Composition: 470 ohms +5%, 1/4 w In REV A & earlier: Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith 100374-DS-8. 19C307169P204 Composition: 680 ohms ±5%, 1/4 w. Metal film: 51.1K ohms ±1%, 1/4 w. 19A701250P369 R104 - - - - - - - - - SOCKETS - - - - - - -Metal film: 10.5K ohms ±1%, 1/4 w. 19A701250P303 XY101 19A701785P6 Contact, electrical. (Quantity 8). Metal film: 10.5K ohms +1%, 1/4 w 19A701250P303 19D424303G1 Helical Resonator. 19A701250P269 Metal film: 5.11K ohms ±1%, 1/4 w Ceramic disc: 150 pF ±20%, 1000 VDCW; sim to RMC Type JF Discap. 3R152P132J Composition: 1.3K ohms +5%, 1/4 w Z103 Frequency network: 400-500 resonant freq. 500 VDCW; sim to Dilectron TC501:NPO:330J:SLAC. Metal film: 5.11K ohms ±1%, 1/4 w 19A701250P269 Z104 19A700106P91 Frequency network: 370-470 resonant freq. 500 VDCW; sim to Dilectron TC501:NPO:390J:SLAC. 19A134666P4 Metal film: 24.9K ohms ±1%, 1/4 w. 19A701250P339 Earlier than REV A: ASSOCIATED ASSEMBLIES Metal film: 24.7K ohms $\pm 1\%$, 1/4 w. 19C3142522472 Metal film: 11.5K ohms ±1%, 1/4 w. 19A701250P307 19A701250P347 Metal film: 30.1K ohms ±1%, 1/4 w. NOTE: When reordering specify ICOM Frequency. 19A700106P73 Composition: 2.7K ohms ±5%, 1/4 w. ---- MISCELLANEOUS -----Y101 19A136999G1 Internally compensated: 1 PPM, 851-870 MHz. 19D424092G1 Shield. 19A701332P1 Insulator disk. (Used with Q103-Q106). ----- SOCKETS -----Can. (Used with L103, T101-T106). XA101 19A129424G2 19A116779P6 Contact, electrical: sim to Molex 08-50-0410. Can. (Used with Z101, Z102). 19B227624G1 19B227620P1 AUDIO PROCESSOR BOARD - - - - - - INTEGRATED CIRCUITS - - - - -Ceramic disc: 150 pF ±20%, 1000 VDCW; sim to RMC Type JF Discap. AR101* 19A116754P2 Linear, Dual 741C OP AMP; sim to MC1458SP1 High Slew Rate OP AMP. n REV A & earlier: Linear: Dual In-Line 8-Pin Minidip package; sim to T1, SN72558 NSC. 19A116754P1 *COMPONENTS ADDED, DELETED OR CHANGED BY PRODUCTION CHANGES

DESCRIPTION

mposition: 22 ohms +5%, 1/4 w

Composition: 10 ohms ±5%, 1/4 w.

Composition: 68 ohms $\pm 5\%$, 1/4 w.

Composition: 10 ohms ±5%, 1/4 w.

Composition: 220 ohms $\pm 5\%$, 1/4 w.

Composition: 10K ohms +5%, 1/4 w.

Composition: 47 ohms $\pm 5\%$, 1/2 w.

Composition: 100 ohms $\pm 5\%$, 1/4 w.

Composition: 10K ohms +5%, 1/4 w.

Composition: 20 ohms $\pm 5\%$, 1/2 w.

Composition: 10K ohms $\pm 5\%$, 1/4 w.

Thermistor: 22.8K ohms ±5%, color code black and orange; sim to Carborundum Type 723B1.

Composition: 15 ohms ±5%, 1/4 w; sim to Allen-Bradley Type CB.

Composition: 10K ohms ±5%, 1/4 w.

SYMBOL

R138

R139

R141

R142

R143

R144

R145

R146

R147

R148

R149

R151

R152

R153 and R154

RT101

GE PART NO.

19A700106P23

19A700106P15

19A700106P35

19A700106P15

19A700106P47

19A700106P87

19A700113P31

19A700106P87

19A116310P35

19A700106P87

3R77P200J

SYMBOL | GE PART NO.

C102

C104

C105

C106

C107

C108

C109

C110

C112*

T644ACP333J

5491674P36

T644ACP347J

644ACP333J

5491674P28

5496267P9

T644ACP268J

9A143481P20

5491674P36

T644ACP368J

19A115250P1

19A143491P6J0

DESCRIPTION

- - - - - - - - - CAPACITORS - - - - - - -

Tantalum: 3.3 uF ±20%, 10 VDCW; sim to Sprague

Tantalum: 1 uF ±20%, 25 VDCW; sim to Sprague

Tantalum: 3.3 uF ±20%, 15 VDCW; sim to Sprague

antalum: 3.3 uF ±20%, 10 VDCW; sim to Sprague vpe 162D.

Ceramic: 6 pF ±5%, temp coef 0 PPM. Added by

- - - - - DIODES AND RECTIFIERS - - - - -

Polyester: 0.033 uF ±5%, 50 VDCW.

Polyester: .047 uF ±5%, 50 VDCW.

Polyester: 0.033 uF ±5%, 50 VDCW.

Polyester: 0.0068 uF ±5%, 50 VDCW.

eramic: 1000 pF ±10%, 1000 VDCW.

Polyester: .068 uF ±5%, 50 VDCW.

Silicon, fast recovery, 225 mA, 50 PIV.

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter," which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

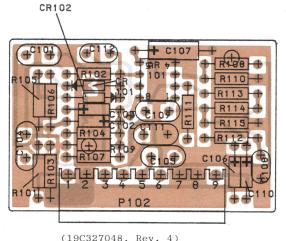
AUDIO PROCESSOR BOARD 19C321524G1

- REV. A Changed value of R112. Changed to standard value.
- REV. B To improve audio response. Changed AR101, R103 and added C112.
- REV. C To correct errors in wiring diagram. Changed AR101 and R103.

EXCITER 19D424075G1

- REV. A To prevent failure of polarized capacitor on 10 V Reg. Board. Changed connection of R106 from ground to +10 Volt Reg.
- REV. B To increase channel guard deviation sensitivity. Changed R101
- REV. C To provide reverse polarity protection for Q107 Base-emitter junction. Added CR103.
- REV. D To increase modulation sensitivity and power output.

 Changed R104 from 19A700106P93 (18K) to 19A700106P89 (12K). Changed C122 from 19A116656P27J8 to 19A116655P19.
- REV. E To improve performance. Changed C161 from 19A116655P7 to Z103 (19A134666P3). Changed C175 from 19A134666P4 to Z104 (19A134666P4).
- REV. F To increase power output, added C176; changed R152. R152 was 3R77P390J: Composition; 39 ohms ±5%, 1/2 W.

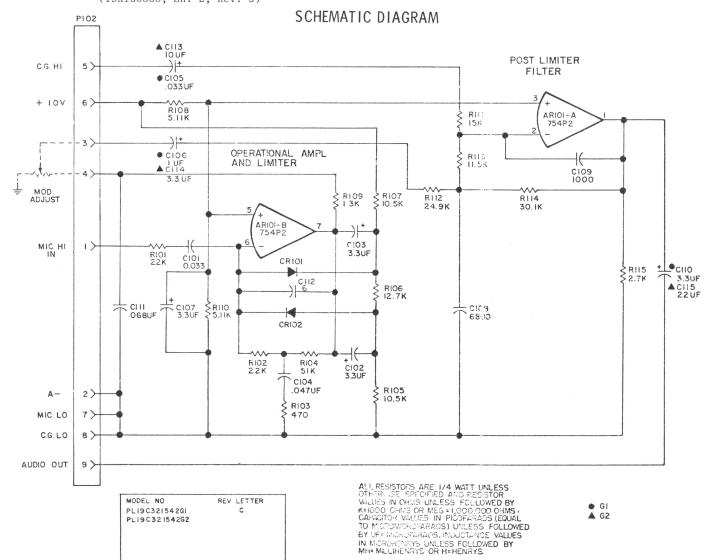


RUNS ON SOLDER SIDE

RUNS ON BOTH SIDES

RUNS ON COMPONENT SIDE

(19C327048, Rev. 4) (19A130538, Sh. 1, Rev. 3) (19A130538, Sh. 2, Rev. 3)



NOTES:

I.CONNECT GRD TO PIN 4 ON ARIOI, CONNECT VCC (+IOV) TO PIN 8 ON ARIOI.

OUTLINE & SCHEMATIC DIAGRAM

AUDIO PROCESSOR